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Contents

ix *Conference Committee*

NOVEL METHODS I

12053 02 **A study on the detection and monitoring of weak areas in wafer using massive 2D and 3D measurement data** [12053-8]

12053 03 **New metrology technique for measuring patterned wafer geometry on a full 300mm wafer** [12053-9]

12053 04 **GHz half wavelength contact acoustic microscopy (HaWaCAM): a feasibility study** [12053-10]

12053 05 **Enhancement of acoustic-wave induced reflection changes through surface plasmon polaritons** [12053-11]

SEM I

12053 06 **Throughput vs. yield: reviewing the metrology needs for stochastics-aware process window analysis (SA-PWA) (Invited Paper)** [12053-13]

12053 07 **Probabilistic process window: a new approach to focus-exposure analysis** [12053-14]

12053 08 **Highlighting stochastic manifestations in 193 nm immersion lithography with contour-based metrology metrics (Karel Urbanek Best Student Paper Award)** [12053-17]

12053 09 **Low dosage SEM image processing for metrology applications** [12053-18]

12053 0A **Simulating process subtleties in SEM imaging** [12053-19]

EPE/OVERLAY I

12053 0B **Fast and robust overlay metrology from visible to infrared wavelengths using dark-field digital holographic microscopy** [12053-25]

12053 0C **Enabling on-device and target-free overlay measurement from CD-SEM contours** [12053-26]

12053 0D **Overlay challenges in 3D heterogeneous integration** [12053-27]

12053 0E **Overlay stability control in IBO measurement using rAIM target** [12053-29]

INSPECTION CHALLENGES

12053 0F **Identification of sub-20 nm EUV defects with nano-IR PiFM** [12053-30]

12053 0G **High-speed wafer magnetic field inspection for semiconductor manufacturing** [12053-31]

12053 0H **EUV mask defect material characterization through actinic lensless imaging** [12053-33]

12053 0I **Defect detection and classification on imec iN5 node BEoL test vehicle with MultiSEM** [12053-34]

12053 0J **Ultra-high throughput e-beam inspection for DRAM high aspect ratio storage node defect detection** [12053-35]

12053 0K **Unbiased roughness measurements from low signal-to-noise ratio SEM images** [12053-64]

GAA AND NANOSHEET

12053 0L **Recess metrology challenges for 3D device architectures in advanced technology nodes** [12053-36]

12053 0M **Inferred measurement of subsurface nanosheet structures using scanning probe microscopy, solving the inverse problem** [12053-37]

EUV CHALLENGES

12053 0N **Optical overlay metrology trends in advanced nodes** [12053-101]

12053 0O **Metrology of thin resist for high NA EUVL** [12053-2]

12053 0P **Low-voltage aberration-corrected SEM metrology of thin resist for high-NA EUVL** [12053-3]

12053 0Q **Outlier analysis for understanding process variations and probable defects** [12053-4]

OPTICAL CD

12053 0S **Vertical travelling scatterometry for metrology on fully integrated devices** [12053-40]

12053 0T **Novel inline on-device measurement of silicon nitride lateral recess post channel hole ACI with IRCD metrology** [12053-42]

12053 0U **A novel methodology for wafer-level scanner focus spot capture and back-tracing mechanism** [12053-153]

MACHINE LEARNING

12053 0V **Regularized autoencoder for the analysis of multivariate metrology data** [12053-44]

12053 0W **Multi-branch neural network for hybrid metrology improvement** [12053-46]

KEYNOTE SESSION II AND KAREL URBÁNEK BEST STUDENT PAPER AWARD ANNOUNCEMENT

12053 0X **Diversifying the role of MI in semiconductor manufacturing through new technologies and innovations (Keynote Paper)** [12053-49]

EPE/OVERLAY II

12053 0Y **Model-less analysis method for characterizing overlay in EUV lithography** [12053-51]

12053 0Z **E-beam metrology-based EUVL aberration monitoring** [12053-52]

12053 10 **Subsurface scanning probe metrology for overlay through opaque layers** [12053-54]

NOVEL METHODS II

12053 11 **Sensitivity and repeatability performance on overlay and CD measurement by incorporating hologram based ellipsometry** [12053-55]

12053 12 **Inline metrology of high aspect ratio hole tilt using small-angle x-ray scattering** [12053-58]

12053 13 **Imaging of buried overlay and alignment markers using picosecond acoustic microscopy** [12053-59]

12053 14 **Advanced CD uniformity correction using radial basis function (RBF) models** [12053-60]

LATE BREAKING NEWS

12053 15 **Absolute overlay measurement based on voltage contrast defect inspection with programmed misalignments for DRAM devices** [12053-149]

12053 16 **Improved multi-lot overlay performance via phase-based ADI overlay measurements** [12053-154]

POSTER SESSION

12053 17 **Efficient cross-sectional evaluation method of three-dimensional NAND flash memory by cooperation of coherence scanning interferometry and scanning electron microscopy** [12053-57]

12053 18 **Overcome machine to machine overlay for better scanner mix-run control** [12053-61]

12053 19 **A comprehensive study of scanner alignment mark quantity and layout-dependent effect for overlay performance optimization** [12053-62]

12053 1A **New DRAM application space for optical AEI metrology enabled by ASML self reference (ASR) targets** [12053-65]

12053 1B **Virtual cross metrology: leveraging process sequence for improved process characterization** [12053-68]

12053 1C **Metrology test artifact availability improvement** [12053-70]

12053 1D **High-performance denoiser based on deep learning trained by precisely reproduced SEM noise** [12053-71]

12053 1E **Prediction and optimization of small scatterometry based overlay targets** [12053-72]

12053 1G **Model-based contour extraction: an enabler for very low-frame SEM images metrology** [12053-75]

12053 1H **OPO reduction in scatterometry metrology by rotated quadrupole illumination** [12053-77]

12053 1I **Adopting combined feed forward solution in HVM fab to improve on product overlay** [12053-78]

12053 1J **Spatial frequency analysis of LER and LWR to tune SADP process** [12053-79]

12053 1K **Image-based alignment sensor unaffected by aberration** [12053-86]

12053 1L **Exposure process optimization using machine learning overlay prediction** [12053-87]

12053 1M **Computational metrology introduction into high volume manufacturing fab through 1x nm uDBO measurement and monitor** [12053-88]

12053 1N **An automated system for detecting systematic defect in memory cell array** [12053-91]

12053 1O **Reduction in on-product overlay random error using machine learning algorithm** [12053-92]

12053 1P **In device overlay control with multiple overlay metrology in 3D-NAND process** [12053-93]

12053 1Q **Machine learning modeling using process context and exposure data for overlay prediction** [12053-94]

12053 1R **Application of machine learning-based metrology for writer main pole CD measurement by CDSEM** [12053-95]

12053 1S **Improved fab-out EDS prediction of memory device using effective accuracy equation** [12053-98]

12053 1T **Using pattern analysis to improve wafer inspection flow** [12053-99]

12053 1U **In-line monitoring of overlay and process window using design-assisted voltage contrast inspection for 14nm FINFET technology** [12053-102]

12053 1V **An in-depth look at comprehensive and efficient methodology for CD uniformity budget breakdown** [12053-103]

12053 1W **Predicting overlay mark performance based on process emulation and optical simulation** [12053-105]

12053 1X **A novel target optimization methodology for 3D NAND overlay measurement improvement** [12053-106]

12053 1Y **Fast generation of SEM images including charging effect by neural network** [12053-107]

12053 1Z **Spectral analysis overlay measurement approach for improvement of overlay accuracy in advanced integrated circuits** [12053-108]

12053 20 **Trilayer hardmask lithography and etch for BEOL manufacturing** [12053-110]

12053 21 **Real-time monitoring of acetic acid and PGMEA in a photolithographic multifunction chemical filter using a laser-based multi-species VOC analyzer** [12053-111]

12053 22 **Process optimization by virtual target design in overlay metrology** [12053-112]

12053 23 **Real-time monitoring of critical AMC compounds in the photolithography cell using a novel laser-based, multi-species detection system** [12053-113]

12053 24 **Depth measurement using high-voltage SEM that changes the inclination of the incident beam** [12053-117]

12053 25 **Efficient metrology for edge placement error (EPE) characterization using design for inspection methodology** [12053-119]

12053 26 **Chemical metrology: a novel approach to measuring critical airborne molecular contamination in photolithography and track tools in real-time** [12053-120]

12053 27 **Automated extraction of critical dimension from SEM with Weave** [12053-121]

12053 28 **Conducting a metrology measurement using M-FOUP system in fab environment** [12053-124]

12053 29 **A new development algorithm to optimize scanner alignment sampling for cross-chuck overlay performance optimization** [12053-152]

12053 2A **Advanced dose control using random logic device patterns and massive metrology in a foundry high-volume manufacturing environment** [12053-155]